

# MOSFET - Power, Single N-Channel, SUPERFET<sup>®</sup>, FAST, TOLL-4L 600 V, 48 mΩ, 50 A

# 600 V, 48 mΩ, 50 A NTBL048N60S5H

## **Description**

The SUPERFET V MOSFET FAST series helps maximize system efficiency by the extremely low switching losses in hard switching application. The TOLL package offers improved thermal performance and excellent switching performance by providing a Kelvin Source configuration and lower parasitic source inductance.

#### Features

- 650 V @  $T_J = 150^{\circ}$ C / Typ.  $R_{DS(on)} = 38.4 \text{ m}\Omega$
- 100% Avalanche Tested
- Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

#### **Applications**

- Telecom / Server Power Supplies
- EV Charger / UPS / Solar / Industrial Power Supplies

# ABSOLUTE MAXIMUM RATINGS (T<sub>J</sub> = 25°C, Unless otherwise noted)

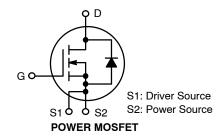
| Parameter   |  | Symbol                            | Value          | Unit |
|---|--|-----------------------------------|----------------|------|
| Drain-to-Source Voltage   |  | $V_{DSS}$                         | 600            | V    |
| Gate-to-Source Voltage  | DC   | $V_{GS}$                          | ±30            | V    |
|   | AC (f > 1 Hz)                              |                                   | ±30            |      |
| Continuous Drain Current  | T <sub>C</sub> = 25°C                      | I <sub>D</sub>                    | 50             | Α    |
|   | T <sub>C</sub> = 100°C                     |                                   | 31             |      |
| Power Dissipation   | T <sub>C</sub> = 25°C                      | $P_{D}$                           | 297            | W    |
| Pulsed Drain Current (Note 1)   | T <sub>C</sub> = 25°C                      | I <sub>DM</sub>                   | 175            | Α    |
| Pulsed Source Current (Body Diode) (Note 1)                             | T <sub>C</sub> = 25°C                      | I <sub>SM</sub>                   | 175            | Α    |
| Operating Junction and Storage Temperature Range                        |  | T <sub>J</sub> , T <sub>STG</sub> | -55 to<br>+150 | °C   |
| Source Current (Body Diode)   |  | Is                                | 50             | Α    |
| Single Pulse Avalanche<br>Energy  | $I_L = 7.6 \text{ A}$<br>$R_G = 25 \Omega$ | E <sub>AS</sub>                   | 478            | mJ   |
| Avalanche Current   |  | I <sub>AS</sub>                   | 7.6            | Α    |
| Repetitive Avalanche Energy (Note 1)                                    |  | E <sub>AR</sub>                   | 2.98           | mJ   |
| MOSFET dv/dt  |  | dv/dt                             | 120            | V/ns |
| Peak Diode Recovery dv/dt (Note 2)                                      |  |                                   | 20             |      |
| Lead Temperature for Soldering Purposes (1/8" from case for 10 seconds) |  | T <sub>L</sub>                    | 260            | °C   |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

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- 1. Repetitive rating: pulse-width limited by maximum junction temperature.
- 2.  $I_{SD} \le 25$  A, di/dt  $\le 200$  A/ $\mu$ s,  $V_{DD} \le 400$  V, starting  $T_J = 25^{\circ}C$ .

| V <sub>(BR)DSS</sub> | R <sub>DS(ON)</sub> MAX | I <sub>D</sub> MAX |
|----------------------|-------------------------|--------------------|
| 600 V                | 48 mΩ @ 10 V            | 50 A               |





#### **MARKING DIAGRAM**



A = Assembly Location
Y = Year
WW = Work Week
ZZ = Assembly Lot Code
NTBL048N60S5H = Specific Device Code

## **ORDERING INFORMATION**

| Device        | Package  | Shipping <sup>†</sup> |
|---------------|----------|-----------------------|
| NTBL048N60S5H | H-PSOF8L | 2000 / Tape &<br>Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

#### THERMAL CHARACTERISTICS

| Parameter                               | Symbol         | Value | Unit |
|---|----------------|-------|------|
| Thermal Resistance, Junction-to-Case    | $R_{	heta JC}$ | 0.42  | °C/W |
| Thermal Resistance, Junction-to-Ambient | $R_{	heta JA}$ | 43    |      |

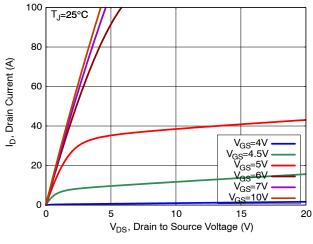
#### **ELECTRICAL CHARACTERISTICS** (T<sub>.1</sub> = 25°C unless otherwise noted)

| Parameter  | Symbol                                     | Test Conditions   | Min | Тур  | Max  | Unit  |
|--|--|---|-----|------|------|-------|
| OFF CHARACTERISTICS  | •  |   |     |      | •    |       |
| Drain-to-Source Breakdown Voltage                            | V <sub>(BR)DSS</sub>                       | $V_{GS} = 0 \text{ V}, I_D = 1 \text{ mA}, T_J = 25^{\circ}\text{C}$      | 600 | _    | -    | V     |
| Drain-to-Source Breakdown Voltage<br>Temperature Coefficient | ΔV <sub>(BR)DSS</sub> /<br>ΔΤ <sub>J</sub> | I <sub>D</sub> = 10 mA, Referenced to 25°C                                | -   | 630  | -    | mV/°C |
| Zero Gate Voltage Drain Current                              | I <sub>DSS</sub>                           | $V_{GS} = 0 \text{ V}, V_{DS} = 600 \text{ V}, T_J = 25^{\circ}\text{C}$  | -   | -    | 2    | μΑ    |
| Gate-to-Source Leakage Current                               | I <sub>GSS</sub>                           | V <sub>GS</sub> = ±30 V, V <sub>DS</sub> = 0 V                            | -   | -    | ±100 | nA    |
| ON CHARACTERISTICS   |  |   |     |      |      |       |
| Drain-to-Source On Resistance                                | R <sub>DS(on)</sub>                        | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 25 A, T <sub>J</sub> = 25°C      | -   | 38.4 | 48   | mΩ    |
| Gate Threshold Voltage                                       | V <sub>GS(th)</sub>                        | $V_{GS} = V_{DS}, I_D = 5.6 \text{ mA}, T_J = 25^{\circ}\text{C}$         | 2.7 | -    | 4.3  | ٧     |
| Forward Trans-conductance                                    | 9FS  | V <sub>DS</sub> = 20 V, I <sub>D</sub> = 25 A                             | -   | 52.3 | -    | S     |
| CHARGES, CAPACITANCES & GATE                                 | RESISTANCE                                 |   |     |      |      |       |
| Input Capacitance  | C <sub>ISS</sub>                           | $V_{DS} = 400 \text{ V}, V_{GS} = 0 \text{ V}, f = 250 \text{ kHz}$       | -   | 5277 | -    | pF    |
| Output Capacitance   | C <sub>OSS</sub>                           |   | -   | 74.3 | -    |       |
| Time Related Output Capacitance                              | C <sub>OSS(tr)</sub>                       | $I_D$ = Constant, $V_{DS}$ = 0 V to 400 V, $V_{GS}$ = 0 V                 | _   | 1173 | -    |       |
| Energy Related Output Capacitance                            | C <sub>OSS(er)</sub>                       | V <sub>DS</sub> = 0 V to 400 V, V <sub>GS</sub> = 0 V                     | -   | 124  | -    |       |
| Total Gate Charge  | Q <sub>G(tot)</sub>                        | V <sub>DD</sub> = 400 V, I <sub>D</sub> = 25 A, V <sub>GS</sub> = 10 V    | -   | 93   | -    | nC    |
| Gate-to-Source Charge  | $Q_{GS}$                                   |   | -   | 25.3 | -    |       |
| Gate-to-Drain Charge   | $Q_{GD}$                                   |   | -   | 23.8 | -    |       |
| Gate Resistance  | $R_{G}$                                    | f = 1 MHz   | -   | 0.66 | -    | Ω     |
| SWITCHING CHARACTERISTICS                                    |  |   |     |      |      |       |
| Turn-On Delay Time   | t <sub>d(on)</sub>                         | $V_{GS} = 0/10 \text{ V}, V_{DD} = 400 \text{ V},$                        | -   | 27.4 | -    | ns    |
| Rise Time  | t <sub>r</sub>                             | $I_D = 25 \text{ A}, R_G = 2.2 \Omega$                                    | -   | 7.69 | -    |       |
| Turn-Off Delay Time  | t <sub>d(off)</sub>                        |   | -   | 76.7 | -    |       |
| Fall Time  | t <sub>f</sub>                             |   | -   | 2.59 | -    |       |
| SOURCE-TO-DRAIN DIODE CHARAC                                 | CTERISTICS                                 |   |     |      |      |       |
| Forward Diode Voltage  | $V_{SD}$                                   | $V_{GS} = 0 \text{ V}, I_{SD} = 25 \text{ A}, T_{J} = 25^{\circ}\text{C}$ | -   | _    | 1.2  | V     |
| Reverse Recovery Time  | t <sub>RR</sub>                            | V <sub>GS</sub> = 0 V, I <sub>SD</sub> = 25 A,                            | -   | 425  | -    | ns    |
| Reverse Recovery Charge                                      | $Q_{RR}$                                   | dl/dt = 100 A/μs, V <sub>DD</sub> = 400 V                                 | -   | 8259 | -    | nC    |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

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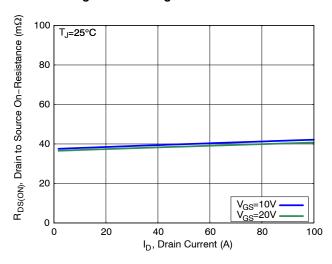
## **TYPICAL CHARACTERISTICS**



1000 V<sub>DS</sub>=20V 100 UELO 1 100 T<sub>J=-55°C</sub> T<sub>J=25°C</sub> T<sub>J=150°C</sub> T<sub>J=</sub>

Figure 1. On-Region Characteristics

Figure 2. Transfer Characteristics



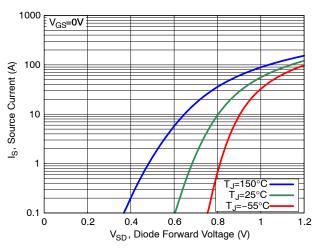
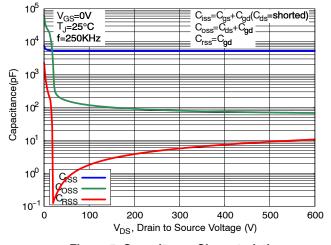


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

Figure 4. Diode Forward Voltage vs. Source Current



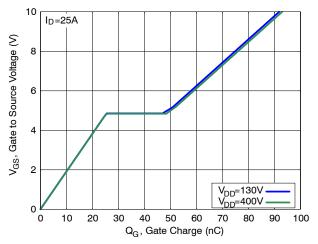


Figure 5. Capacitance Characteristics

Figure 6. Gate Charge Characteristics

#### **TYPICAL CHARACTERISTICS**

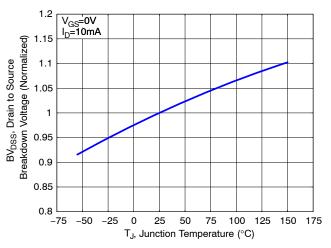


Figure 7. Breakdown Voltage Variation vs. Temperature

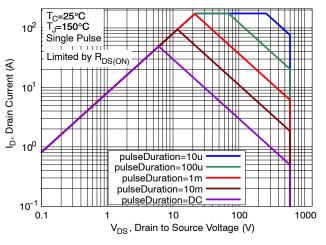


Figure 9. Maximum Safe Operating Area

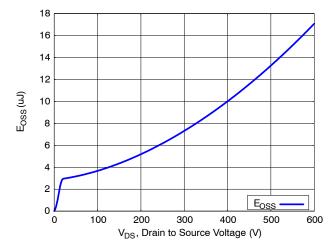


Figure 11. Eoss vs. Drain-to-Source Voltage

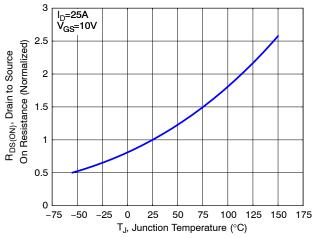


Figure 8. On–Resistance Variation vs.
Temperature

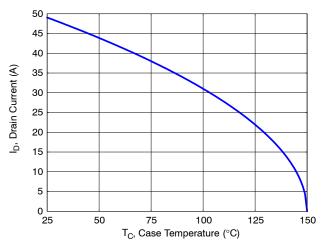


Figure 10. Maximum Drain Current vs. Case Temperature

# **TYPICAL CHARACTERISTICS**

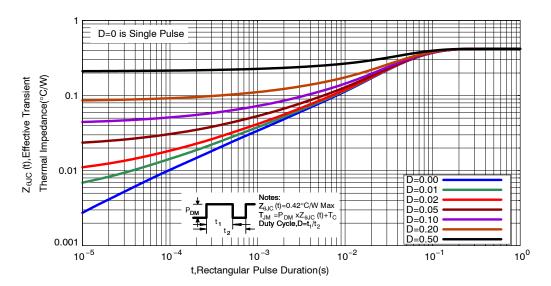
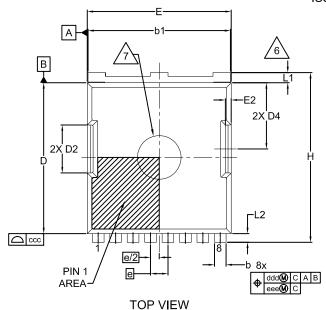


Figure 12. Transient Thermal Impedance

# **PACKAGE DIMENSIONS**

# H-PSOF8L 9.90x11.68, 1.20P

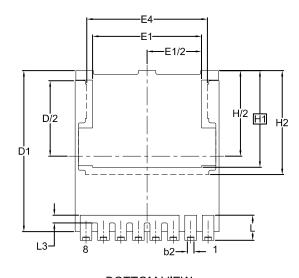
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# BOTTOM VIEW

#### NOTES:

|     | MILLIMETERS      |          |       |
|-----|------------------|----------|-------|
| DIM | MIN.             | NOM.     | MAX.  |
| Α   | 2.20             | 2.30     | 2.40  |
| A1  | 1.70             | 1.80     | 1.90  |
| b   | 0.70             | 0.80     | 0.90  |
| b1  | 9.70             | 9.80     | 9.90  |
| b2  | 0.35             | 0.45     | 0.55  |
| С   | 0.40             | 0.50     | 0.60  |
| D   | 10.28            | 10.38    | 10.48 |
| D1  | 10.98            | 11.08    | 11.18 |
| D2  | 3.20             | 3.30     | 3.40  |
| D/2 | 5.09             | 5.19     | 5.29  |
| D4  | 4.45             | 4.55     | 4.65  |
| Е   | 9.80             | 9.90     | 10.00 |
| E1  | 7.40             | 7.50     | 7.60  |
| E2  | 0.30             | 0.40     | 0.50  |
| E4  | 8.20 8.30 8.40   |          | 8.40  |
| е   |                  | 1.20 BSC |       |
| Н   | 11.58 11.68 11.7 |          | 11.78 |
| H1  | 6.66 BSC         |          |       |
| H2  | 7.05             | 7.15     | 7.25  |
| H/2 | 5.79             | 5.89     | 5.99  |
| L   | 1.63             | 1.73     | 1.83  |
| L1  | 0.60             | 0.70     | 0.80  |
| L2  | 0.50             | 0.60     | 0.70  |
| L3  | 0.43 0.53 0.63   |          |       |
| θ   | 10° REF.         |          |       |
| aaa | 0.20             |          |       |
| ccc | 0.20             |          |       |

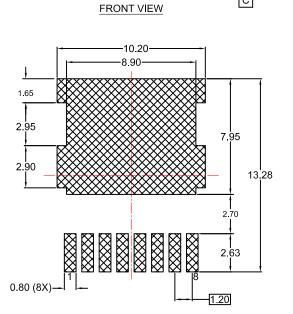
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